


1 Substrate: 1.59mm \pm 0.18mm [0.0625" \pm 0.007"]
FR4/G10 or equivalent high temp material. non clad

2 Pins: material- Brass Alloy 360 1/2 hard; finish-
0.25 μ m [10 μ] Au over 1.27 μ m [50 μ] Ni (min.).

Description: Giga-snaP BGA SMT Land Socket

100 position BGA surface mount land pattern to terminal pins (0.8mm centers, 16x11 array)

Tolerances: diameters \pm 0.03mm [\pm 0.001"], PCB perimeters \pm 0.13mm [\pm 0.005"], PCB thicknesses \pm 0.18mm [\pm 0.007"], pitches (from true position) \pm 0.08mm [\pm 0.003"], all other tolerances \pm 0.13mm [\pm 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

LS-BGA100L-61 Drawing		Status: Released	Scale: 8:1	Rev: B
 <p>© 2012 IRONWOOD ELECTRONICS, INC. Tele: (800) 404-0204 www.ironwoodelectronics.com</p>	Drawing: E. Smolentseva		Date: 2/10/12	
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